

Gate resistor installed Dual N-channel MOSFET

KFC4B21080L Datasheet

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1. GENERAL DESCRIPTION

Gate resistor installed Dual N-channel MOSFET
For lithium-ion secondary battery protection circuits

2. FEATURES

- Low source-source ON Resistance: $R_{ss(on)}$ typ. = 27 m Ω (V_{GS} = 4.5 V)
- CSP (Chip Size Package)
- RoHS compliant (EU RoHS / MSL: Level 1)

3. MARKING SYMBOL: 12

4. PACKAGING

Embossed type (Thermo-compression sealing): 20,000 pcs / reel (standard)

5. ABSOLUTE MAXIMUM RATINGS $T_a = 25^\circ\text{C}$

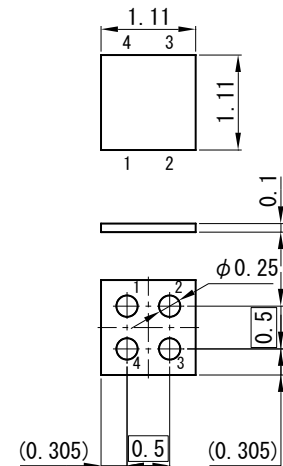
Parameter	Symbol	Rating	Unit
Source-source Voltage	VSS	12	V
Gate-source Voltage	VGS	± 12	V
Source Current (DC) ^{*1}	IS	2.9	A
Source Current (Pulsed) ^{*1,*2}	ISp	29	A
Total Power Dissipation ^{*1}	PD	0.35	W
Channel Temperature	Tch	150	$^\circ\text{C}$
Storage Temperature Range	Tstg	-55 to +150	$^\circ\text{C}$

6. THERMAL CHARACTERISTICS $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Thermal Resistance (ch-a)	Rth ^{*1}	352	$^\circ\text{C} / \text{W}$

Note ^{*1} Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm),
using the minimum recommended pad size (Cu area = 47 mm² including traces).
^{*2} t = 10 μs , Duty Cycle $\leq 1\%$

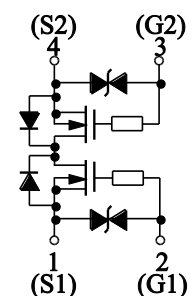
■ Package dimension Unit: mm



1. Source (FET1) 3. Gate (FET2)
2. Gate (FET1) 4. Source (FET2)

Package	ULGA004-W-1212
JEITA	—
Code	—

■ Equivalent circuit, Pin name



1. Source (FET1) 3. Gate (FET2)
2. Gate (FET1) 4. Source (FET2)

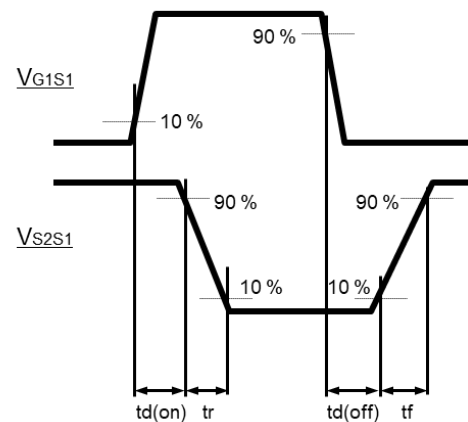
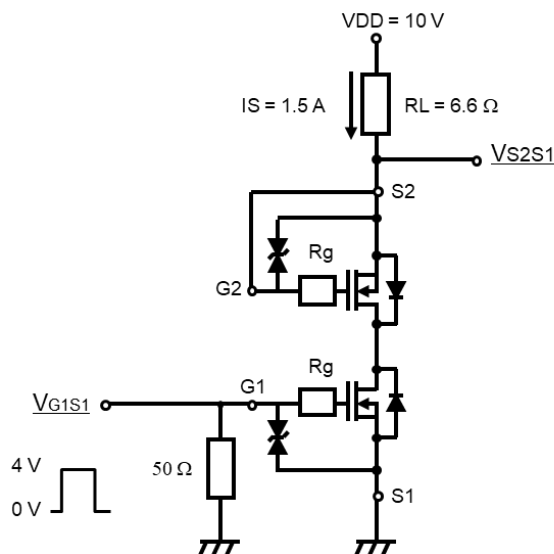
7. ELECTRICAL CHARACTERISTICS $T_a = 25\text{ }^{\circ}\text{C} \pm 3\text{ }^{\circ}\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	12			V
Zero Gate Voltage Source Current	ISSS	VSS = 12 V, VGS = 0 V			1.0	μA
Gate-Source Leakage Current	IGSS	VGS = ± 8 V, VSS = 0 V			± 10	μA
		VGS = ± 5 V, VSS = 0 V			± 1.0	
Gate-source Threshold Voltage	Vth	IS = 1.0 mA, VSS = 10 V	0.40	0.85	1.40	V
Source-source On-state Resistance	RSS(on)1	IS = 1.5 A, VGS = 4.5 V	18.0	27.0	37.0	m Ω
	RSS(on)2	IS = 1.5 A, VGS = 3.8 V	21.0	30.0	41.5	
	RSS(on)3	IS = 1.5 A, VGS = 3.1 V	23.0	39.0	64.0	
	RSS(on)4	IS = 1.5 A, VGS = 2.5 V	30.0	60.0	100	
Input Capacitance *1	Ciss	VSS = 10 V, VGS = 0 V, f = 1 kHz		850		pF
Output Capacitance *1	Coss			205		
Reverse Transfer Capacitance *1	Crss			203		
Turn-on delay Time *1,*2	td(on)	VDD = 10 V, VGS = 0 to 4 V		0.6		μs
Rise Time *1,*2	tr	IS = 1.5 A		1.7		
Turn-off delay Time *1,*2	td(off)	VDD = 10 V, VGS = 4 to 0 V		2.6		μs
Fall Time *1,*2	tf	IS = 1.5 A		3.1		
Total Gate Charge *1	Qg	VDD = 10 V		7.1		nC
Gate-source Charge *1	Qgs	VGS = 0 to 4 V		1.5		
Gate-drain Charge *1	Qgd	IS = 2.9 A		2.7		
Body Diode Forward Voltage	VF(s-s)	IF = 2.9 A, VGS = 0 V		0.8	1.2	V

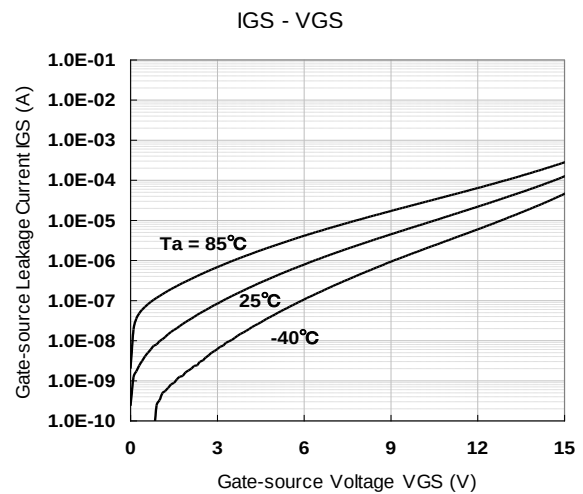
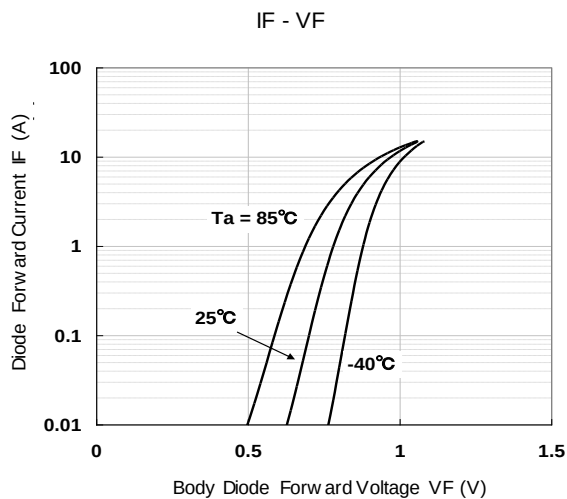
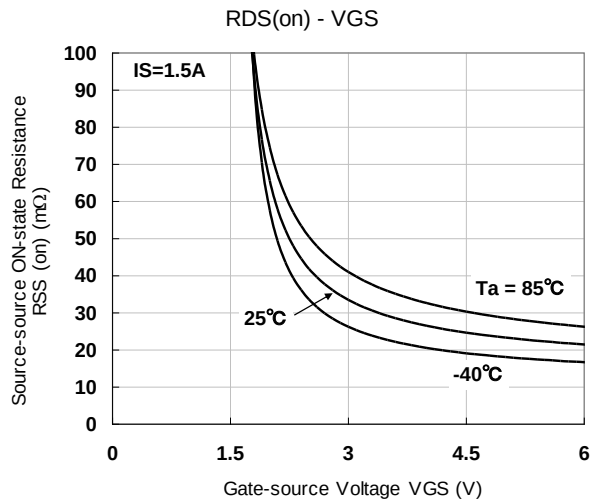
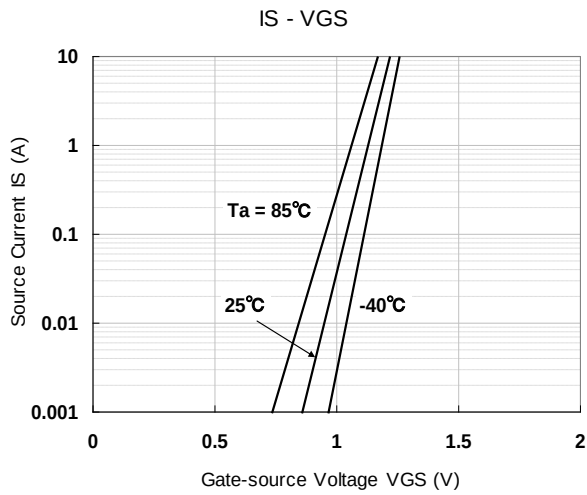
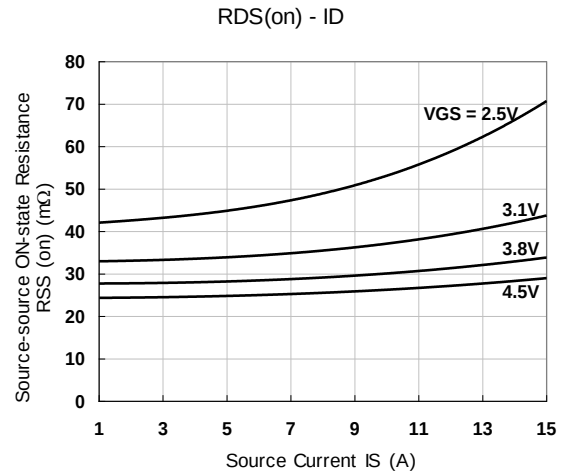
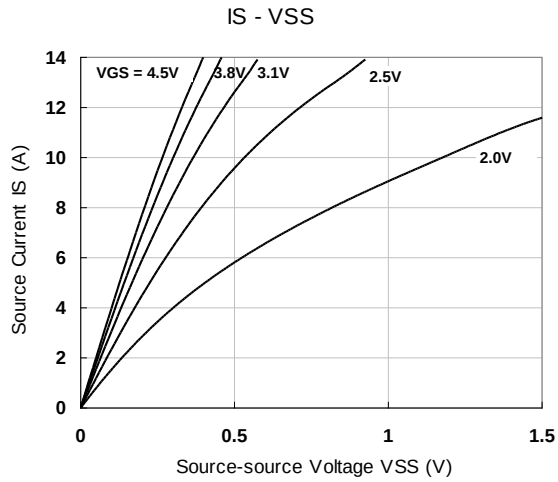
Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

*1 Assured by design

*2 Measurement circuit for Turn-on Delay Time / Rise time / Turn-off Delay Time / Fall Time

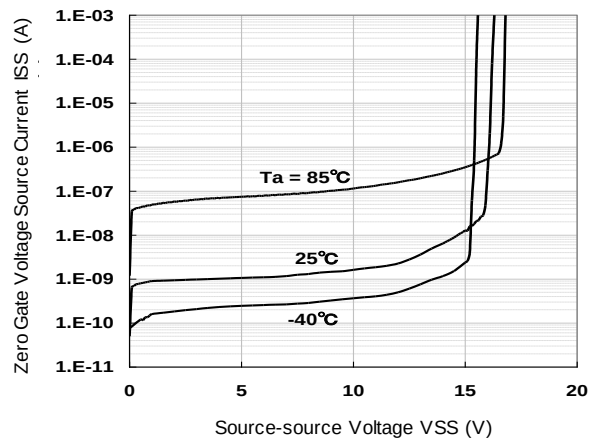


8. TECHNICAL DATA (Reference)



TECHNICAL DATA (Reference)

ISSS - VSSS

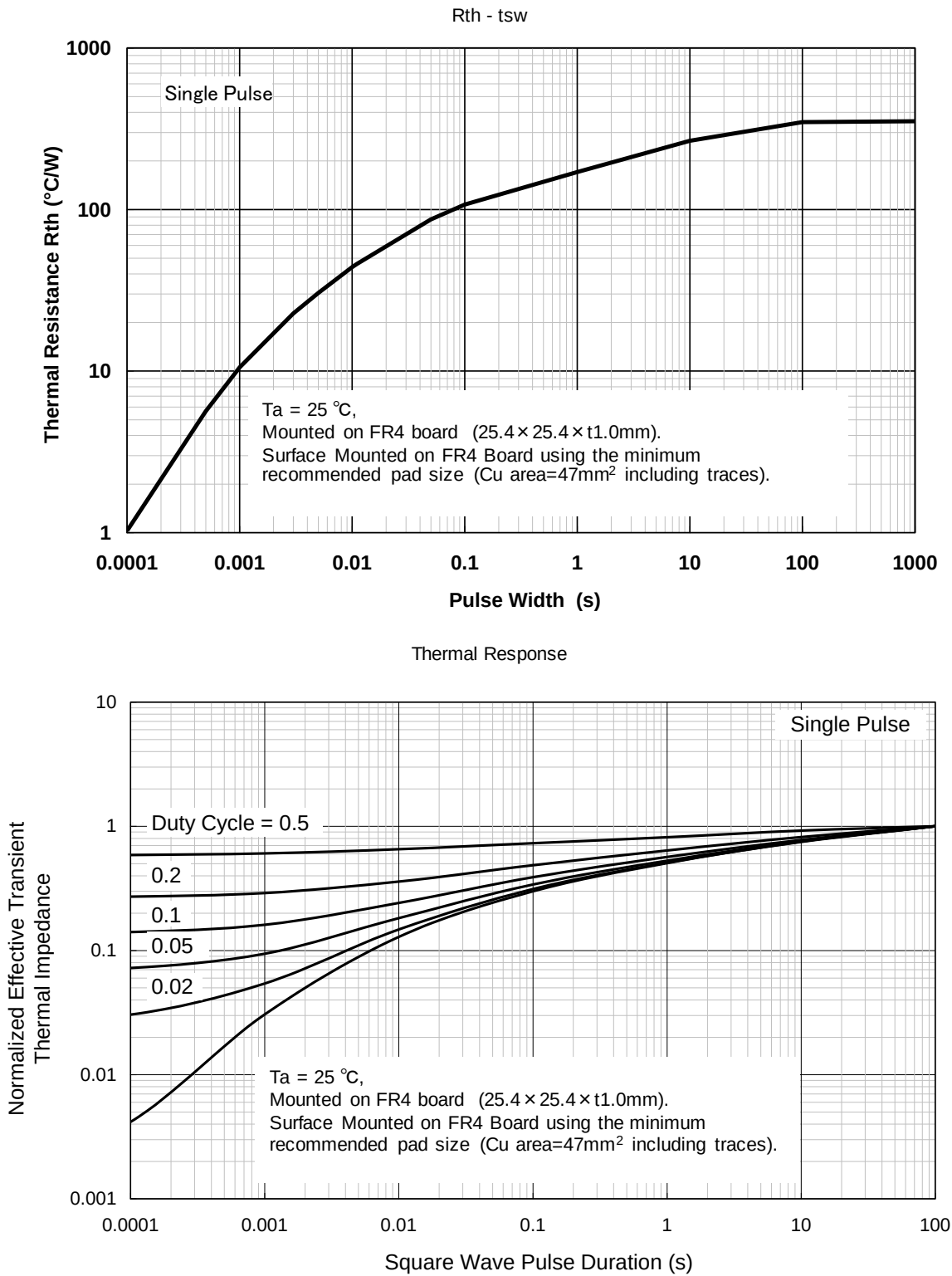


Destruction Current

Parameter	Conditions	Result
Operation Test ^{*1}	VGS = 3.8 V, IS = 12 A, t = 3 ms	PASS
	VGS = 3.8 V, IS = 4.5 A, t = 11 ms	PASS
Destruction Current ^{*1}	VGS = 3.8 V, t = 3 ms	31 A
	VGS = 3.8 V, t = 11 ms	16 A

Ta = 25 °C,
Mounted on FR4 board (25.4 mm × 25.4 mm × t1.0 mm)
using the minimum recommended pad size
(Cu area = 47 mm2 including traces).

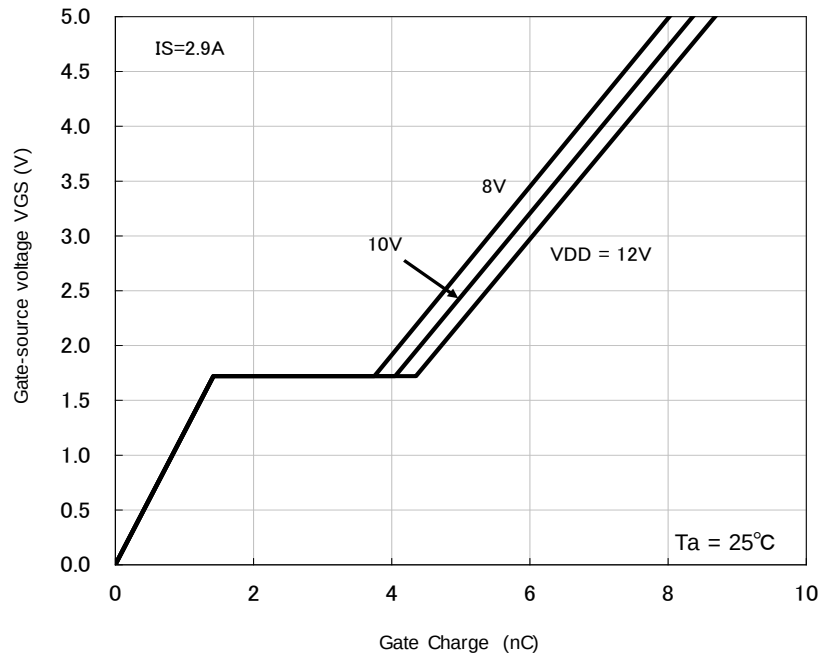
TECHNICAL DATA (Reference)



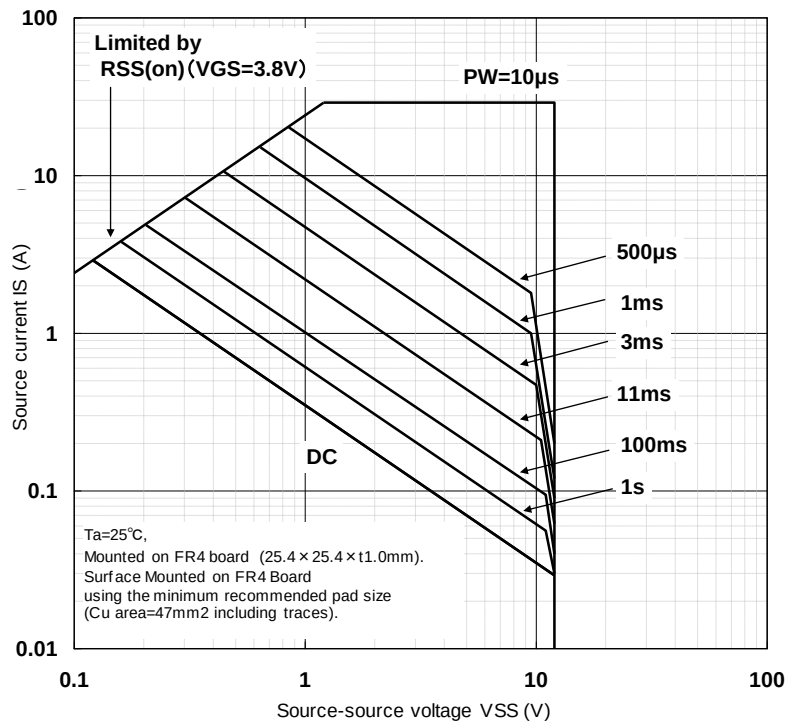
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TECHNICAL DATA (Reference)

Dynamic Input/Output Characteristics

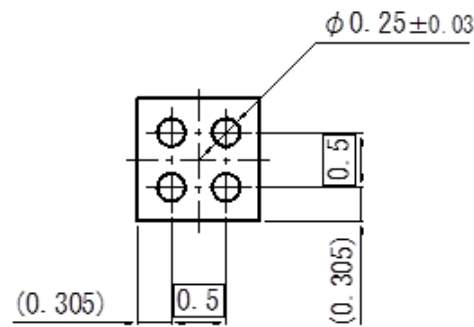
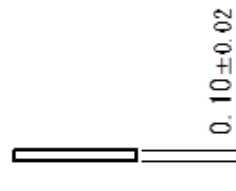
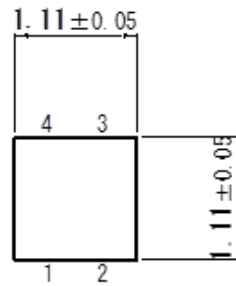


Safe Operating Area



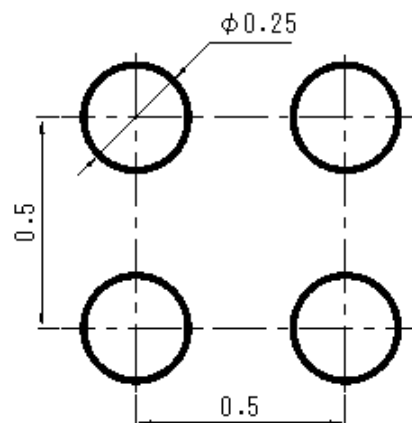
9. OUTLINE

Unit: mm



10. LAND PATTERN (Reference)

Unit: mm



Important notice:

Solder Mask Defined (SMD) pattern is strongly recommended for pad design.
Please check the information in the Nuvoton WL-CSP Application Notes about mounting process.

11. REVISION HISTORY

Date	Revision	Description
2021.02.05	1.00	1. Initially issued.
2021.08.31	1.01	1. Changed document name from Product Standards to Datasheet. 2. Added important notice in Land Pattern. 3. Added special attention and precautions notes.

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